

Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claim 1 (currently amended): A multi-chip package device with a heat sink, comprising:

a chip carrier;

at least one first chip mounted on and electrically connected to a surface of the chip carrier;

at least one semiconductor package mounted on and electrically connected to the surface of the chip carrier, ~~wherein the semiconductor package is slightly thicker than the first chip~~; and

the heat sink mounted via an adhesion layer on a surface of the first chip and a surface of the semiconductor package that are opposite to surfaces of the first chip and the semiconductor package mounted on the chip carrier, ~~wherein a portion of the heat sink attached to the first chip is made thicker than another portion of the heat sink mounted on the semiconductor package, and at least one wherein a plurality of hollow parts extending through the heat sink is are formed at a location of the heat sink subjected to greatest thermal stresses, and the plurality of hollow parts are formed symmetrically at an area of the heat sink free of contact with the first chip and the semiconductor package to release thermal stresses from the heat sink through the at least one hollow part that remains hollow, wherein the size of the hollow part is adjusted depending on the thickness of the heat sink to effectively release the thermal stresses from the heat sink.~~

Claim 2 (original): The multi-chip package device of claim 1, wherein the semiconductor package is a flip-chip ball grid array package.

Claim 3 (original): The multi-chip package device of claim 1, wherein the first chip is a graphic chip.

Claim 4 (original): The multi-chip package device of claim 1, wherein the first chip is a graphic processing unit.

Claim 5 (original): The multi-chip package device of claim 1, wherein the semiconductor package is a Random Access Memory (RAM) unit.

Claim 6 (original): The multi-chip package device of claim 1, wherein the first chip is mounted at the center of the chip carrier, and the semiconductor package is mounted at a position on the chip carrier corresponding to a corner of the heat sink.

Claim 7 (original): The multi-chip package device of claim 1, wherein at least one pair of the semiconductor packages are mounted on the chip carrier, and the hollow part of the heat sink is located between the semiconductor packages.

Claim 8 (original): The multi-chip package device of claim 1, wherein at least one symmetrical pair of the hollow parts are formed through the heat sink.

Claims 9-18 (canceled)

Claim 19 (new): The multi-chip package device of claim 1, wherein a size of each of the hollow parts is adjusted depending on a thickness of the heat sink to effectively release the thermal stresses from the heat sink.